ABSTRACT

A film adhesive containing: an epoxy resin (A); an epoxy resin curing agent (B); and a phenoxy resin (C),

wherein a content of the epoxy resin curing agent (B) in the film adhesive is 0.30 to 12.0 mass%; and

wherein a light transmittance T1 of the film adhesive at a wavelength of 400 nm is 90% or less, a light transmittance T2 of a cured product obtained by thermally curing the film adhesive at a wavelength of 400 nm is 85% or more, and T1 < T2 is satisfied.

(Fig. 1)